



Prof. Takafumi (Tak) Fukushima

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Takafumi Fukushima received his Ph.D. degree in the Department of Materials Science and Chemical Engineering from Yokohama National University in 2003. From 2004 to 2009, he was an assistant professor at the Department of Bioengineering and Robotics at Tohoku University. Since 2010, he has been an associate professor at the New Industry Creation Hatchery Center (NICHe), Tohoku University. From 2016 to 2017 and 2022, He was a visiting faculty at CHIPS (Center for Heterogeneous Integration and Performance Scaling), Electrical Engineering Department, UCLA. He is currently working on Flexible Hybrid Electronics (FHE) and 3D-IC/chiplet holistic system integration with TSV/hybrid and advanced bonding technology at the Department of Biomechanical Engineering, Tohoku University, as a professor. He is also a head of 3D Packaging Technology Division, Leading-edge Semiconductor Technology Center (LSTC). He has been a senior member of the IEEE and Interconnections sub-committee of ECTC since 2013.